# **N-Channel Power MOSFET 600 V, 0.95** Ω

## Features

- Low ON Resistance
- Low Gate Charge
- ESD Diode–Protected Gate
- 100% Avalanche Tested
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant



# **ON Semiconductor®**

## www.onsemi.com

V <sub>DSS</sub>	R <sub>DS(ON)</sub> (MAX) @ 3.5 A
600 V	0.95 Ω

	N-Channel
	D (2) <b>O</b>
G	
	O S (3)
	MARKING DIAGRAM
	$\circ$
NDF08N60ZG, NDF08N60ZH	
TO-220FP CASE 221AH	NDF08N60ZG or
CASE 22TAH	NDF08N60ZH AYWW
	Gate
	U U U Drain
A = Location Y = Year WW = Work We G, H = Pb-Free	
	,

# ABSOLUTE MAXIMUM RATINGS (T<sub>C</sub> = 25°C unless otherwise noted)

Rating	Symbol	NDF08N60Z	Unit
Drain-to-Source Voltage	V <sub>DSS</sub>	600	V
Continuous Drain Current $R_{\theta JC}$ (Note 1)	I <sub>D</sub>	8.4	А
Continuous Drain Current $R_{\theta JC}$ T <sub>A</sub> = 100°C (Note 1)	Ι <sub>D</sub>	5.3	A
Pulsed Drain Current, V <sub>GS</sub> @ 10 V	I <sub>DM</sub>	30	A
Power Dissipation	PD	36	W
Gate-to-Source Voltage	V <sub>GS</sub>	±30	V
Single Pulse Avalanche Energy, I <sub>D</sub> = 7.5 A	E <sub>AS</sub>	235	mJ
ESD (HBM) (JESD 22–A114)	V <sub>esd</sub>	4000	V
$\begin{array}{l} \text{RMS Isolation Voltage} \\ (t=0.3 \text{ sec., R.H.} \leq 30\%, \\ \text{T}_{\text{A}}=25^{\circ}\text{C}) \text{ (Figure 14)} \end{array}$	V <sub>ISO</sub>	4500	V
Peak Diode Recovery (Note 2)	dv/dt	4.5	V/ns
Continuous Source Current (Body Diode)	۱ <sub>S</sub>	7.5	А
Maximum Temperature for Soldering Leads	ΤL	260	°C
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	–55 to 150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Limited by maximum junction temperature 2. I\_D  $\leq$  7.5 A, di/dt  $\leq$  200 A/µs, V\_DD  $\leq$  BV\_DSS, T\_J  $\leq$  150°C.

## **ORDERING INFORMATION**

See detailed ordering and shipping information on page 5 of this data sheet.

# THERMAL RESISTANCE

Parameter	Symbol	NDF08N60Z	Unit
Junction-to-Case (Drain)	$R_{ ext{ heta}JC}$	3.5	°C/W
Junction-to-Ambient Steady State (Note 3)	$R_{\thetaJA}$	50	

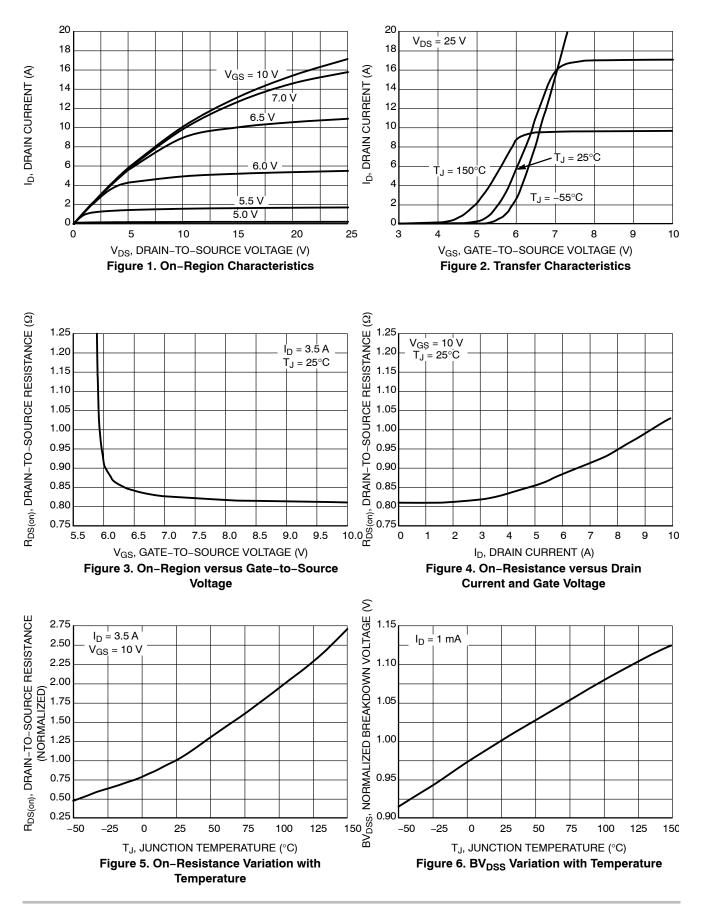
3. Insertion mounted

# **ELECTRICAL CHARACTERISTICS** (T<sub>J</sub> = $25^{\circ}$ C unless otherwise noted)

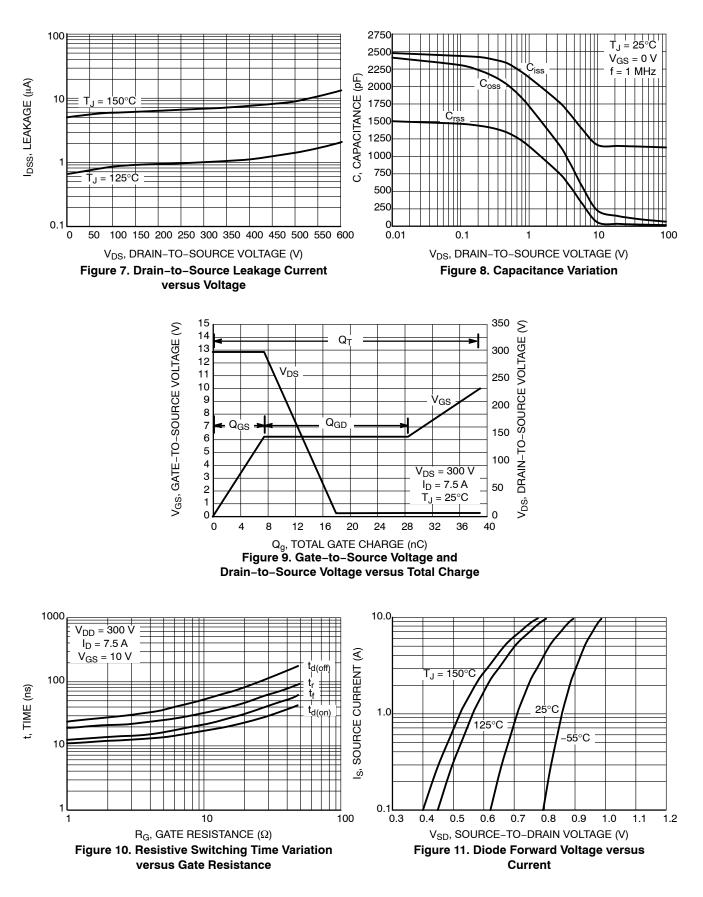
Characteristic	Test Conditions	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS		•		•	•	•
Drain-to-Source Breakdown Voltage	$V_{GS}$ = 0 V, $I_D$ = 1 mA	BV <sub>DSS</sub>	600			V
Breakdown Voltage Temperature Co- efficient	Reference to $25^{\circ}$ C, I <sub>D</sub> = 1 mA	$\Delta BV_{DSS}/\Delta T_{J}$		0.6		V/°C
Drain-to-Source Leakage Current	$V_{DS} = 600 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$ 125	000			1 50	μΑ
Gate-to-Source Forward Leakage	V <sub>GS</sub> = ±20 V	I <sub>GSS</sub>			±10	μΑ
ON CHARACTERISTICS (Note 4)					1	
Static Drain-to-Source On-Resistance	$V_{GS}$ = 10 V, I <sub>D</sub> = 3.5 A	R <sub>DS(on)</sub>		0.82	0.95	Ω
Gate Threshold Voltage	$V_{DS}$ = $V_{GS}$ , $I_D$ = 100 $\mu$ A	V <sub>GS(th)</sub>	3.0	3.9	4.5	V
Forward Transconductance	$V_{DS} = 15 \text{ V}, \text{ I}_{D} = 3.5 \text{ A}$	9 <sub>FS</sub>		6.3		S
OYNAMIC CHARACTERISTICS						
Input Capacitance (Note 5)		C <sub>iss</sub>	913	1140	1370	pF
Output Capacitance (Note 5)	$V_{DS} = 25 \text{ V}, \text{ V}_{GS} = 0 \text{ V},$	C <sub>oss</sub>	105	129	160	
Reverse Transfer Capacitance (Note 5)	f = 1.0 MHz	C <sub>rss</sub>	20	30	40	
Total Gate Charge (Note 5)		Qg	20	39	58	nC
Gate-to-Source Charge (Note 5)		Q <sub>gs</sub>	4	7.5	11.5	
Gate-to-Drain ("Miller") Charge (Note 5)	$\label{eq:VDD} \begin{array}{l} V_{\text{DD}} = 300 \; V, \; I_{\text{D}} = 7.5 \; A, \\ V_{\text{GS}} = 10 \; V \end{array}$	Q <sub>gd</sub>	10	21	31	1
Plateau Voltage		V <sub>GP</sub>		6.2		V
Gate Resistance		Rg		1.6		Ω
RESISTIVE SWITCHING CHARACTERI	STICS	-				
Turn-On Delay Time		t <sub>d(on)</sub>		14		ns
Rise Time	V <sub>DD</sub> = 300 V, I <sub>D</sub> = 7.5 A,	t <sub>r</sub>		22		1
Turn-Off Delay Time	$V_{GS}$ = 10 V, $R_{G}$ = 5 $\Omega$	t <sub>d(off)</sub>		36		1
Fall Time		t <sub>f</sub>		15		<u> </u>
SOURCE-DRAIN DIODE CHARACTER	STICS (T <sub>C</sub> = 25°C unless otherwise	e noted)				
Diode Forward Voltage	I <sub>S</sub> = 7.5 A, V <sub>GS</sub> = 0 V	V <sub>SD</sub>			1.6	V
Reverse Recovery Time	V <sub>GS</sub> = 0 V, V <sub>DD</sub> = 30 V	t <sub>rr</sub>		320		ns
Reverse Recovery Charge	I <sub>S</sub> = 7.5 A, di/dt = 100 A/μs	Q <sub>rr</sub>		2.2		μC

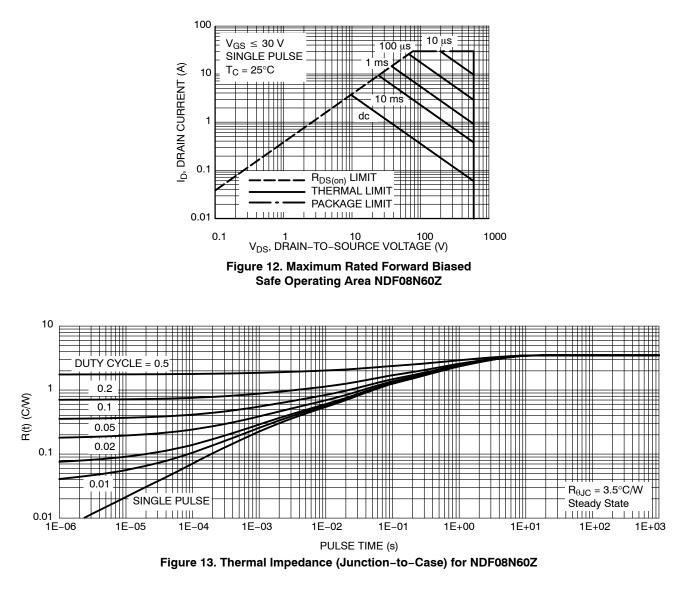
Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.
4. Pulse Width ≤ 380 µs, Duty Cycle ≤ 2%.
5. Guaranteed by design.

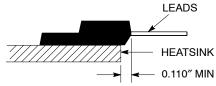
# **TYPICAL CHARACTERISTICS**



# **TYPICAL CHARACTERISTICS**







### Figure 14. Isolation Test Diagram

Measurement made between leads and heatsink with all leads shorted together.

\*For additional mounting information, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

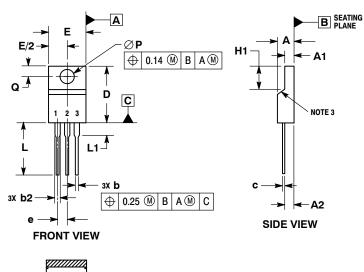
#### **ORDERING INFORMATION**

Order Number	Package	Shipping
NDF08N60ZG	TO-220FP (Pb-Free, Halogen-Free)	50 Units / Rail
NDF08N60ZH	TO-220FP (Pb-Free, Halogen-Free)	50 Units / Rail

### PACKAGE DIMENSIONS

## TO-220 FULLPACK, 3-LEAD CASE 221AH

**ISSUE F** 



NOTE 6

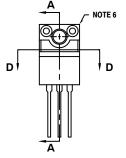
**SECTION A-A** 

NOTES: DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.

- 2. CONTROLLING DIMENSION: MILLIMETERS. 3. CONTOUR UNCONTROLLED IN THIS AREA.
- DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH AND GATE PROTRUSIONS. MOLD FLASH AND GATE PROTRUSIONS NOT TO 4.
- EXCEED 0.13 PER SIDE. THESE DIMENSIONS ARE TO BE MEASURED AT OUTERMOST EXTREME OF THE PLASTIC BODY. DIMENSION b2 DOES NOT INCLUDE DAMBAR PROTRUSION. LEAD WIDTH INCLUDING PROTRUSION SHALL NOT EXCEED 2.00.
- CONTOURS AND FEATURES OF THE MOLDED PACKAGE BODY MAY VARY WITHIN THE ENVELOP DEFINED BY DIMENSIONS A1 AND H1 FOR MANUFACTURING PURPOSES. 6.

AND THE OTHMANOLAOTON			
MILLIMETERS			
MIN	MAX		
4.30	4.70		
2.50	2.90		
2.50	2.90		
0.54	0.84		
1.10	1.40		
0.49	0.79		
14.70	15.30		
9.70	10.30		
2.54 BSC			
6.60	7.10		
12.50	14.73		
	2.80		
3.00	3.40		
2.80	3.20		
	MIN           4.30           2.50           2.50           0.54           1.10           0.49           14.70           9.70           2.54           6.60           12.50              3.00	MILLIMETERS           MIN         MAX           4.30         4.70           2.50         2.90           0.54         0.84           1.10         1.40           0.49         0.79           14.70         15.30           9.70         10.30           2.54         BSC           6.60         7.10           12.50         14.73            2.80           3.00         3.40	

SECTION D-D



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